

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20140304002B Qualification of HNT and JCET Chuzhou as Additional Assembly/Test Site for Select Devices Change Notification / Sample Request

Dear Customer:

Version B of this PCN is to notify that there will be no change on the wire type for Group 3 devices. Affected devices will use existing wire type during assembly process.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services Phone: +1(214) 480-6037

Fax: +1(214) 480-6659

PCN# 20140304002B Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

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PCN Number:				20140304002B				PCN Dat	te:	04/03/2014	
Title	Title: Qualification of HNT and JCET Chuzhou as Additional Assembly/Test Site for Select Devices							e for Select			
Cust	omer	Contact:	PC	N Ma	anager P	hone	+1(214)480-	6037	Dept:	Qua	ality Services
Char	ige T	ype:							•		
		mbly Site			Assembly	Proce	ess		Assembly	Mat	erials
	Desi				Electrical						ecification
\boxtimes	Test	Site			Packing/S	Shippir	ng/Labeling		Test Proce	ess	
	Wafe	er Bump Site			Wafer Bu				Wafer Bur	mp F	rocess
	Wafe	er Fab Site			Wafer Fa				Wafer Fab	Pro	cess
					Part num						
_						<u>PCN</u>	Details				
Desc	riptio	on of Change	:								
Affec Quali	<mark>ted de</mark> ficatio	evices will use on of HNT and	ex JC	<mark>istir</mark> ET (ng wire type Chuzhou as	e durir Additi	ng assembly pro onal Assembly/	ocess).		Group 3 devices. Devices.
Mate	rial di	fferences betv	vee	n A	ssembly/Te	st site	s as follows:				
Grou	p 1 [Devices: Asse	ml	bly	Site chang	je onl	y. No Assemb	ly m	aterial diff	fere	nces.
Grou	p 2 [Devices:			NCE		HANA		7		
	Mal	d Compound			NSE	\	HANA		4		
	MOI	d Compound			CZ0140	,	450176				
Grou	ın 3 E	Devices :									
					NFME		JCETCZ		7		
	Mol	d Compound			R-15		0131020244	01	1		
	Wir	e Type			<mark>Au</mark>		Cu		1		
		age, insertions	s, c	ond	itions will r	emain	consistent with	ı cur	- rent testing	and	l verified with
test N	ИQ.										
Reas	on fo	or Change:									
Conti	nuity	of Supply									
Antio	cipate	ed impact on	Fc	rm	Fit, Func	tion, (Quality or Reli	abili	ity (positiv	/e /	negative):
None	•	• • • • • • • • • • • • • • • • • • • •		<u> </u>	•	,	<u> </u>				- 3
		to product id	on	+ifi,	ation rocu	ulting	from this PCN				
		nd 2 Devices		LITIC	ation rest	iitiiig	Hom this PCN	1.			
		y Site	_								
	E Tha				Assem	nbly Si	te Origin (22L)		AS	1:08	VSE
		ailand					te Origin (22L)			50: I	
ASS	EMBL	Y SITE CODES	S:	NSE	=J, HAN	4 = H		•			
Gro	up 3	Devices:									
		y Site									
	ME Cl					Ass	embly Site Orig	gin (2	22L)	AS	O: NFM
	JCET Chuzhou China Assembly Site Origin (22L) ASO: GP6							O: GP6			
ASS	EMBL	Y SITE CODES	S:	NFM	$IE = \overline{E, JCE}$	TCZ =	=F				

Sample product shipping label (not actual product label)



MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT:

LBL: 5A (L)TO:3750



(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483812

(2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

Group 1	Product	Affected:
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_	•			
	TPS61040DDCR	TPS62240DDCT	TPS62260DDCT	TPS62561DDCR
	TPS61040DDCT	TPS62240DDCTG4	TPS62260DDCTG4	TPS62561DDCT
	TPS62240DDCR	TPS62260DDCR	TPS62262DDCR	
	TPS62240DDCRG4	TPS62260DDCRG4	TPS62262DDCT	

Group 2 Product Affected:

TPS62230DRYR	TPS622314DRYR	TPS62231DRYR	TPS62236DRYR
TPS62230DRYT	TPS622314DRYT	TPS62231DRYT	TPS62236DRYT
TPS622310DRYR	TPS622315DRYR	TPS62232DRYR	TPS62237DRYR
TPS622310DRYT	TPS622315DRYT	TPS62232DRYT	TPS62237DRYT
TPS622311DRYR	TPS622316DRYR	TPS62233DRYR	TPS62238DRYR
TPS622311DRYT	TPS622316DRYT	TPS62233DRYT	TPS62238DRYT
TPS622312DRYR	TPS622317DRYR	TPS62234DRYR	TPS62239DRYR
TPS622312DRYT	TPS622317DRYT	TPS62234DRYT	TPS62239DRYT
TPS622313DRYR	TPS622318DRYR	TPS62235DRYR	
TPS622313DRYT	TPS622318DRYT	TPS62235DRYT	

Group 3 Product Affected:

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	CD4051BE	LM339N	LM393P	ULN2003AN
	LM324N	LM358P	NE555P	
	LM324NE3	LM358PE3	SN74HC164N	

Group 1 Qualification Data

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle: TPS62260DDCR (MSL1-260C)

Qual Vehicle: 11 302200DER (11321 2000)							
Package Construction Details							
Assembly Site:	HNT	Mold Compound:	450207				
# Pins-Designator, Family:	5-DDC, SOT	Mount Compound:	400151				
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia. Au				
Qualification: Plan							

Qualification:	ot results	
Reliability Test	Conditions	Sample Size / Fail
Electrical Characterization	-	15/0

Refer	rence	Ou	ıali	fica	ation:

Qual Vehicle 1: TPS62220DDC (MSL1-260C)							
	Package Cor		•	-,			
Assembly Site:	HNT	Mold Compo		ound: 450207		50207	
# Pins-Designator, Family:	5-DDC, SOT		Mount Compo			00151	
Lead Finish, Base	NiPdAu, Cu		Bond			0 Mil Dia.	Au
	X Test Results		20114			0 1 2	7.0
Reliability Test	Condition	าร		S	am	ple Size /	Fail
	gon and a	.0		Lot#		Lot# 2	Lot# 3
**Autoclave	121C, 2	atm (2	40 Hrs)	77/0		77/0	77/0
**Temperature Cycle	-65/150			77/0		77/0	77/0
**Thermal Shock	-65/150			77/0		77/0	77/0
X-ray	(top side	only)	•	5/0		5/0	5/0
Flammability	Method A			5/0		5/0	5/0
Flammability	Method E			5/0		5/0	5/0
Flammability		Method C - UL 1694				5/0	5/0
Manufacturability (Assembly)		(per mfg. Site specification)			5	Pass	Pass
Moisture Sensitivity		@ 2600	260C peak +5/-0C))	12/0	12/0
**- Preconditioning sequence:							
Qua			DCK (MSL1-260	C)			
	Package Cor	struct	ion Details				
Assembly Site:	HNT		Mold Compo		45	50207	
# Pins-Designator, Family:	5-DCK, SOT		Mount Compo	ound:	40	0151	
Lead Finish, Base	NiPdAu, Cu		Bond	Wire: 1.25 Mil Dia. Au			a. Au
Qualification: Plan	▼ Test Results						
Reliability Test	Condition	าร		S	am	ple Size /	Fail
				Lot#	1	Lot# 2	Lot# 3
**Autoclave	121C, 2	atm (2	40 Hrs)	77/0)	77/0	77/0
**Temperature Cycle	-65/150			77/0		77/0	77/0
**Thermal Shock	-65/150			77/0		77/0	77/0
**HAST	130C/85		,	77/0		77/0	77/0
**Life test	155C (24			116/		116/0	116/0
**High-Temp Storage Bake		170C (420 Hrs)		77/0		77/0	77/0
Manufacturability (Assembly) (per mfg. Site specification) Pass Pass Pass							
**- Preconditioning sequence:							
Group 2 Oualification Data							

Group 2 Qualification Data

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

validates that the proposed change meets the applicable released technical specifications.								
Qua	Qual Vehicle: TPS62234DRYT (MSL1-260C)							
Package Construction Details								
Assembly Site:	HNT	Mold Compo	ound:	450176				
# Pins-Designator, Family:	6-DRY, SON	, SON Mount Compo		400173				
Lead Finish, Base	NiPdAu, Cu	Bond Wire:		1.0 Mil Dia. Au				
Qualification: Plan	▼ Test Results							
Reliability Test	Conditions	Conditions		ample Size / Fail				
Electrical Characterization	-	-		15/0				
Manufacturability (Assembly)	(per mfg. Site	specification)		Pass				

Reference Qualification:

Qual Vehicle 1: TPD4S014DRY (MSL1-260C)							
	Pac	kage Construct	tion Details	-			
Assembly Site:	HNT	Mold Comp		ound: 450176			
# Pins-Designator, Family:	6-DRY	, SON	Mount Comp			00173	
Lead Finish, Base			Bond	Wire:	1.	0 Mil Dia.	Au
•		Results					
Reliability Test		Conditions		S	am	ple Size /	Fail
·				Lot#	1	Lot# 2	Lot# 3
X-ray		(top side only)		5/0		5/0	5/0
Manufacturability (Assembly)		(per mfg. Site s		Pass	3	Pass	Pass
Moisture Sensitivity		(Level 1 @ 260	C peak +5/-0C)	12/0)	12/0	12/0
**- Preconditioning sequence:							
Qual	Vehicle	e 2: TS3A4415	9RSV (MSL1-260	C)			
	Pac	kage Construct	ion Details				
Assembly Site:	HNT	Mold Comp		ound: 450176			
# Pins-Designator, Family: 16-RS		V, QFN	Mount Compo	ound:	40	00173	
Lead Finish, Base	NiPdAu	ı, Cu				Au	
Qualification: Plan	X Test	Results					
Reliability Test		Conditions				nple Size / Fail	
				Lot#	1	Lot# 2	Lot# 3
**Life Test		150C (300 Hrs)		116/	0	116/0	116/0
**Biased HAST		130C/85%RH (96 Hrs)		77/0		77/0	77/0
**Autoclave		121C, 2 atm (96 Hrs)		77/0		77/0	77/0
**Temperature Cycle		-65/150 (1000		77/0)	77/0	77/0
**High-Temp Storage Bake		150C (1000 Hrs)		77/0)	77/0	77/0
Flammability		Method UL94-V0		5/0		5/0	5/0
Flammability		Method IEC 695-2-2		5/0		5/0	5/0
Flammability		Method UL-1694		5/0		5/0	5/0
X-ray	(top side only)		5/0		5/0	5/0	
Salt Atmosphere	-		22/0		22/0	22/0	
Manufacturability (Assembly)		(per mfg. Site specification)		Pass		Pass	Pass
Moisture Sensitivity		(Level 1 @ 260	C peak $+\overline{5/-0C}$	12/0)	12/0	12/0
**- Preconditioning sequence: Level 1-260C.							

Group 3 Qualification Data

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

valuates that the proposed thange meets the applicable released testimed speciments.							
Qual Vehicle 1: LM358P							
Package Construction Details							
Assembly Site:	JCET CHUZHOU	Mold Compound:	013102024401				
# Pins-Designator, Family:	8-N, PDIP	Mount Compound:	011204001701				
Lead Finish, Base	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia. Cu				

Reliability Test	Qualification: Plan Test Results								
Pass	Reliability Test	Conditions		Sample Size / Fail					
Autoclave				Lot#	1 Lot# 2	Lot# 3			
Temperature Cycle	Electrical Characterization	-		Pass	-	-			
Biased HAST	Autoclave	121C, 2 atm (192 Hrs)		77/0	-	-			
High Temp. Storage Bake									
Life Test 150C (300 hrs) 77/0 Salt Atmosphere 24 Hrs 22/0 22/0 22/0 22/0 Scray (top side only) 5/0 5/0 5/0 5/0 Solderability 8 Hours Steam Age 22/0 22/0 22/0 22/0 Solderability Method A - UL94-0 Solderability Method B - IEC 695-2-2 Solderability Method B - IEC 695-2-2 Solderability Solderability Method C - UL 1694 Solderability Solderability Method C - UL 1694 Solderability Solderability Method C - UL 1694 Solderability Soldera		- `	. , ,			77/0			
Salt Atmosphere 24 Hrs 22/0 22/0 22/0 X-ray (top side only) 5/0 5/0 5/0 Solderability 8 Hours Steam Age 22/0 22/0 22/0 Flammability Method A - UL94-0 5/0 5/0 5/0 Flammability Method B - IEC 695-2-2 5/0 5/0 5/0 Flammability (Assembly) (per mfg. Site specification) Pass Pass Pass Manufacturability (Assembly) (per mfg. Site specification) Pass Pass Pass Package Construction Details Assembly Site: JCET CHUZHOU Mold Compound: 013102024401 # Pins-Designator, Family: 14-N, PDIP Mount Compound: 011204001701 Lead Finish, Base Matte Sn, Cu Bond Wire: 1.0 Mil Dia. Cu Qualification: Plan Test Results Reliability Test Conditions Sample Size / Fail Lot# 1 Lot# 2 Lot# 3 Electrical Characterization - Pass <td< td=""><td>High Temp. Storage Bake</td><td>` '</td><td colspan="2">,</td><td>-</td><td>-</td></td<>	High Temp. Storage Bake	` '	,		-	-			
X-ray						-			
Solderability	Salt Atmosphere	24 Hrs				22/0			
Flammability		` ' '				5/0			
Method B - IEC 695-2-2 5/0 5/0 5/0 5/0 Flammability Method C - UL 1694 5/0 5/	Solderability			22/0		22/0			
Method C - UL 1694 5/0 5/0 5/0 Manufacturability (Assembly) (per mfg. Site specification) Pass Pas	,								
Manufacturability (Assembly) (per mfg. Site specification) Pass Pass Pass Qual Vehicle 2: SN74HC164N Package Construction Details Assembly Site: JCET CHUZHOU Mold Compound: 013102024401 # Pins-Designator, Family: 14-N, PDIP Mount Compound: 011204001701 Lead Finish, Base Matte Sn, Cu Bond Wire: 1.0 Mil Dia. Cu Qualification: Plan ▼ Test Results Reliability Test Conditions Sample Size / Fail Lot# 1 Lot# 1 Lot# 2 Lot# 3 Electrical Characterization - Pass - Autoclave 121C, 2 atm (240 Hrs) 77/0 - - Life Test 150C (300 hrs) 77/0 - - Temperature Cycle -65/150 (1000 cycles) 77/0 - - Biased HAST 130C/85%RH (192 Hrs) 77/0 - - High Temp. Storage Bake 170C (600 Hrs) 77/0 - -	Flammability	Method B - IEC 695-2-2							
Qual Vehicle 2: SN74HC164N Package Construction Details Assembly Site: JCET CHUZHOU Mold Compound: 013102024401 # Pins-Designator, Family: 14-N, PDIP Mount Compound: 011204001701 Lead Finish, Base Matte Sn, Cu Bond Wire: 1.0 Mil Dia. Cu Qualification: Plan Test Results Sample Size / Fail Lot# 1 Lot# 2 Lot# 3 Electrical Characterization - Pass - Autoclave 121C, 2 atm (240 Hrs) 77/0 - Life Test 150C (300 hrs) 77/0 - Temperature Cycle -65/150 (1000 cycles) 77/0 - Biased HAST 130C/85%RH (192 Hrs) 77/0 - High Temp. Storage Bake 170C (600 Hrs) 77/0 - X-ray (top side only) 5/0 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0 22/0	lammability Method C - UL 1694		5/0	5/0	5/0				
Package Construction Details Assembly Site: JCET CHUZHOU Mold Compound: 013102024401 # Pins-Designator, Family: 14-N, PDIP Mount Compound: 011204001701 Lead Finish, Base Matte Sn, Cu Bond Wire: 1.0 Mil Dia. Cu Qualification: Plan Test Results Reliability Test Conditions Sample Size / Fail Lot# 1 Lot# 2 Lot# 3 Electrical Characterization - Pass - Autoclave 121C, 2 atm (240 Hrs) 77/0 - Life Test 150C (300 hrs) 77/0 - Temperature Cycle -65/150 (1000 cycles) 77/0 - Biased HAST 130C/85%RH (192 Hrs) 77/0 - High Temp. Storage Bake 170C (600 Hrs) 77/0 - X-ray (top side only) 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0			(per mfg. Site specification)		Pass	Pass			
Assembly Site: JCET CHUZHOU Mold Compound: 013102024401 # Pins-Designator, Family: 14-N, PDIP Mount Compound: 011204001701 Lead Finish, Base Matte Sn, Cu Bond Wire: 1.0 Mil Dia. Cu Qualification: Plan Test Results Reliability Test Conditions Sample Size / Fail Lot# 1 Lot# 2 Lot# 3 Electrical Characterization - Pass - Autoclave 121C, 2 atm (240 Hrs) 77/0 - Life Test 150C (300 hrs) 77/0 - Temperature Cycle -65/150 (1000 cycles) 77/0 - Biased HAST 130C/85%RH (192 Hrs) 77/0 - High Temp. Storage Bake 170C (600 Hrs) 77/0 - X-ray (top side only) 5/0 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0 22/0	Qual Vehicle 2: SN74HC164N								
# Pins-Designator, Family: 14-N, PDIP Mount Compound: 011204001701 Lead Finish, Base Matte Sn, Cu Bond Wire: 1.0 Mil Dia. Cu Qualification: □ Plan ☑ Test Results Reliability Test Conditions Sample Size / Fail Lot# 1 Lot# 2 Lot# 3 Electrical Characterization - Pass Autoclave 121C, 2 atm (240 Hrs) 77/0 Life Test 150C (300 hrs) 77/0 Temperature Cycle -65/150 (1000 cycles) 77/0 Biased HAST 130C/85%RH (192 Hrs) 77/0 High Temp. Storage Bake 170C (600 Hrs) 77/0 X-ray (top side only) 5/0 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0	Package Construction Details								
Lead Finish, Base Matte Sn, Cu Bond Wire: 1.0 Mil Dia. Cu Qualification: Plan Test Results Reliability Test Conditions Sample Size / Fail Lot# 1 Lot# 2 Lot# 3 Electrical Characterization - Pass Autoclave 121C, 2 atm (240 Hrs) 77/0 Life Test 150C (300 hrs) 77/0 Temperature Cycle -65/150 (1000 cycles) 77/0 Biased HAST 130C/85%RH (192 Hrs) 77/0 High Temp. Storage Bake 170C (600 Hrs) 77/0 X-ray (top side only) 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0	Assembly Site: JCET	CHUZHOU	Mold Comp	ound:	und: 013102024401				
Qualification: Plan Test Results Reliability Test Conditions Sample Size / Fail Lot# 1 Lot# 2 Lot# 3 Electrical Characterization - Pass - Autoclave 121C, 2 atm (240 Hrs) 77/0 - - Life Test 150C (300 hrs) 77/0 - - Temperature Cycle -65/150 (1000 cycles) 77/0 - - Biased HAST 130C/85%RH (192 Hrs) 77/0 - - High Temp. Storage Bake 170C (600 Hrs) 77/0 - - X-ray (top side only) 5/0 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0	# Pins-Designator, Family: 14-N	, PDIP	Mount Comp	ound:	011204001	11204001701			
Reliability Test Conditions Sample Size / Fail Lot# 1 Lot# 2 Lot# 3 Electrical Characterization - Pass - - Autoclave 121C, 2 atm (240 Hrs) 77/0 - - Life Test 150C (300 hrs) 77/0 - - Temperature Cycle -65/150 (1000 cycles) 77/0 - - Biased HAST 130C/85%RH (192 Hrs) 77/0 - - High Temp. Storage Bake 170C (600 Hrs) 77/0 - - X-ray (top side only) 5/0 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0			Bond	Wire:	1.0 Mil Dia.	0 Mil Dia. Cu			
Lot# 1 Lot# 2 Lot# 3	Qualification: Plan Test Results								
Electrical Characterization - Pass - Autoclave 121C, 2 atm (240 Hrs) 77/0 - Life Test 150C (300 hrs) 77/0 - Temperature Cycle -65/150 (1000 cycles) 77/0 - Biased HAST 130C/85%RH (192 Hrs) 77/0 - High Temp. Storage Bake 170C (600 Hrs) 77/0 - X-ray (top side only) 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0	Reliability Test	Conditions				' Fail			
Autoclave 121C, 2 atm (240 Hrs) 77/0 - - Life Test 150C (300 hrs) 77/0 - - Temperature Cycle -65/150 (1000 cycles) 77/0 - - Biased HAST 130C/85%RH (192 Hrs) 77/0 - - High Temp. Storage Bake 170C (600 Hrs) 77/0 - - X-ray (top side only) 5/0 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0				Lot#	1 Lot# 2	Lot# 3			
Life Test 150C (300 hrs) 77/0 - - Temperature Cycle -65/150 (1000 cycles) 77/0 - - Biased HAST 130C/85%RH (192 Hrs) 77/0 - - High Temp. Storage Bake 170C (600 Hrs) 77/0 - - X-ray (top side only) 5/0 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0	Electrical Characterization				-	-			
Temperature Cycle -65/150 (1000 cycles) 77/0 - - Biased HAST 130C/85%RH (192 Hrs) 77/0 - - High Temp. Storage Bake 170C (600 Hrs) 77/0 - - X-ray (top side only) 5/0 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0	Autoclave	121C, 2 atm (240 Hrs)		77/0	-	-			
Biased HAST 130C/85%RH (192 Hrs) 77/0 - - High Temp. Storage Bake 170C (600 Hrs) 77/0 - - X-ray (top side only) 5/0 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0	Life Test	150C (300 hrs)		77/0	-	-			
High Temp. Storage Bake 170C (600 Hrs) 77/0 - - X-ray (top side only) 5/0 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0	Temperature Cycle			77/0	-	-			
X-ray (top side only) 5/0 5/0 5/0 Solderability Pb Free/Solder 22/0 22/0 22/0	Biased HAST			77/0	-	-			
Solderability Pb Free/Solder 22/0 22/0 22/0	High Temp. Storage Bake					-			
				5/0	5/0	5/0			
Manufacturability (Assembly) (per mfg. Site specification) Pass Pass Pass					•	•			
	Manufacturability (Assembly)	(per mfg. Site specification)		Pass	Pass	Pass			

Qual Vehicle 3: CD4051BE								
Package Construction Details								
Assembly Site:	JCET CHUZHOU		Mold Compound:		013102024401			
# Pins-Designator, Family:	16-N, PDIP		Mount Compound:		011204001701			
Lead Finish, Base	Matte	Sn, Cu	Bond Wire:		1.0 Mil Dia. Cu			
Qualification: Plan	$oxed{oxed}$ Test	Results						
Reliability Test		Conditions			Sample Size / Fail			
				Lot#	1 Lot# 2	Lot# 3		
Electrical Characterization		-		Pass		-		
Autoclave		121C, 2 atm (2	•	77/0		77/0		
Temperature Cycle		-65/150 (1000		77/0		77/0		
Biased HAST	130C/85%RH (77/0		77/0		
High Temp. Storage Bake	170C (600 Hrs)			77/0		77/0		
X-ray	(top side only)			5/0		5/0		
Solderability	8 Hours Steam			22/0		22/0		
Flammability	Method A - UL9			5/0	5/0	5/0		
Flammability	Method B - IEC			5/0		5/0		
ammability Method C - UL :			5/0	5/0	5/0			
Manufacturability (Assembly)	(per mfg. Site s			Pass	Pass	Pass		
Qual Vehicle 4: ULN2003AN								
Package Construction Details								
Assembly Site:	JCET CHUZHOU		Mold Compound:					
# Pins-Designator, Family:	16-N, PDIP		Mount Compound:		011204001701			
Lead Finish, Base	Matte Sn, Cu		Bond Wire:		1.0 Mil Dia. Cu			
Qualification: Plan Test Results								
Reliability Test	Conditions				ample Size / Fail			
			Lot#		Lot# 3			
Biased HAST		130C/85%RH (192 Hrs)		77/0		77/0		
Manufacturability (Assembly)	(per mfg. Site specification)		Pass	Pass	Pass			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com